



PCB LAYOUT

SPECIFICATIONS

Current Rating: 3A AC, DC
 Voltage Rating: 250V AC, DC
 Temperature Range: -25°C ~ +85°C
 Contact Resistance: 10mΩ Max
 Insulation Resistance: 1000MΩ Min
 Withstanding Voltage: 1000V AC/minute
 Material: Wafer LCP, UL94V-0
 PIN Brass Tin-plated
 Solder tabs Brass Tin-plated

P数	A	B	C	D
02	2.50	7.50	10.00	8.20
03	5.00	10.00	12.50	10.70
04	7.50	12.50	15.00	13.20
05	10.00	15.00	17.50	15.70
06	12.50	17.50	20.00	18.20
07	15.00	20.00	22.50	20.70
08	17.50	22.50	25.00	23.20
09	20.00	25.00	27.50	25.70
10	22.50	27.50	30.00	28.20
11	25.00	30.00	32.50	30.70
12	27.50	32.50	35.00	33.20
15	35.00	40.00	42.50	40.70

一般公差 TOLERANCES X .±0.40 .XX ±0.20 .X ±0.30 .XXX ±0.10 ANGLES ±2°		深圳市宏利电子有限公司 Shenzhen Holy Electronic Co.,Ltd	
检验尺寸标示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	工程图号 XH25WB-nP	制图 (DR) *12/5/16 审核 (CHKD)	
表面处理 (FINISH)	比例 (SCALE) 1:1	单位 (UNITS) mm	核准 (APPD) Rigo Lu 张数 (SHEET) 1 OF 1 尺寸 (SIZE) A4 版数 (REV) 0

修订 REV	修改摘要 REVISION DESCRIPTION	日期 DATE	签名 SIGNATURE
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